

HOSTAFORM®

Chemical abbreviation according to ISO 1043-1: POM Molding compound ISO 29988- POM-K, M-GNR, 02-003, GF20 POM copolymer Injection molding type, reinforced with ca. 20 % glass fibers; high resistance to thermal and oxidative degradation; reduced thermal expansion and shrinkage. UL-registration in natural and black and a thickness more than 1.5 mm as UL 94 HB, temperature index UL 746 B, electrical 105 °C, mechanical 105 °C Burning rate ISO 3795 and FMVSS 302 < 100 mm/min for a thickness more than 1 mm thickness. Ranges of applications: For molded parts with high strength and rigidity as well as higher hardness. FMVSS = Federal Motor Vehicle Safety Standard (USA) UL = Underwriters Laboratories (USA)

Product information

1 Toddot Information			
Resin Identification	POM		ISO 1043
Part Marking Code	>POM<		ISO 11469
Rheological properties			
Melt volume-flow rate	4.5	cm ³ /10min	ISO 1133
Temperature	190	°C	
Load	2.16	kg	
Moulding shrinkage, parallel	0.7	%	ISO 294-4, 2577
Moulding shrinkage, normal	1.1	%	ISO 294-4, 2577
Typical mechanical properties			
Tensile modulus	7200	MPa	ISO 527-1/-2
Tensile stress at break, 5mm/min	120	MPa	ISO 527-1/-2
Tensile strain at break, 5mm/min	3	%	ISO 527-1/-2
Flexural modulus	6900	MPa	ISO 178
Flexural strength	170	MPa	ISO 178
Flexural strain at failure	3.4	%	ISO 178
Tensile creep modulus, 1h	6500	MPa	ISO 899-1
Tensile creep modulus, 1000h	4000	MPa	ISO 899-1
Charpy impact strength, 23°C	35	kJ/m²	ISO 179/1eU
Charpy impact strength, -30°C	40	kJ/m²	ISO 179/1eU
Charpy notched impact strength, 23°C	8	kJ/m²	ISO 179/1eA
Charpy notched impact strength, -30°C	8	kJ/m²	ISO 179/1eA
Ball indentation hardness, H 358/30	190	MPa	ISO 2039-1
Poisson's ratio	0.434		
Thermal properties			
Melting temperature, 10°C/min	166	°C	ISO 11357-1/-3
Temperature of deflection under load, 1.8 MPa	159	°C	ISO 75-1/-2
Temperature of deflection under load, 8 MPa	105		ISO 75-1/-2
Coefficient of linear thermal expansion		E-6/K	ISO 11359-1/-2
(CLTE), parallel			
Coefficient of linear thermal expansion (CLTE),	80	E-6/K	ISO 11359-1/-2
normal			





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Flammability				
Burning Behav. at 1.5mm nom. thickn.		HB	class	IEC 60695-11-10
Thickness tested		-	mm	IEC 60695-11-10
Burning Behav. at thickness h			class	IEC 60695-11-10
Thickness tested			mm	IEC 60695-11-10
UL recognition		yes		UL 94
Electrical properties				
Relative permittivity, 100Hz		4.3		IEC 62631-2-1
Relative permittivity, 1MHz		4.3		IEC 62631-2-1
Dissipation factor, 100Hz			E-4	IEC 62631-2-1
Dissipation factor, 1MHz			E-4	IEC 62631-2-1
Volume resistivity			Ohm.m	IEC 62631-3-1
Surface resistivity		1E14		IEC 62631-3-2
Electric strength			kV/mm	IEC 60243-1
Comparative tracking index		600		IEC 60112
Physical/Other properties				
Humidity absorption, 2mm		0.19	%	Sim. to ISO 62
Water absorption, 2mm		0.85		Sim. to ISO 62
Density		1550	kg/m³	ISO 1183
Injection				
Drying Recommended		no		
Drying Temperature		100	°C	
Drying Time, Dehumidified Dryer		3 - 4	h	
Processing Moisture Content		≤0.2	%	
Melt Temperature Optimum		200	°C	
Min. melt temperature		190		
Max. melt temperature		210	-	
Screw tangential speed		≤0.3		
Mold Temperature Optimum		100		
Min. mould temperature			°C	
Max. mould temperature		120 60 - 120		
Hold pressure range			MPa MPa	
Back pressure		2	IVIFa	
Characteristics				
Processing	Injection Moulding			

Delivery form

Additives

Pellets

Release agent





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Additional information

Injection molding

Preprocessing

General drying is not necessary due to low moisture absorption of the resin.

In case of bad storage conditions (water contact or condensed water) the use of a recirculating air dryer (100 to 120 °C / max. 40 mm layer / 3 to 6 hours) is recommended.

Max. Water content 0,2 %

Processing

Standard injection moulding machines with three phase (15 to 25 D) plasticating screws will fit.

Postprocessing

Conditioning e.g. moisturizing is not necessary.

Processing Notes

Pre-Drying

Drying is not normally required. If material has come in contact with moisture through improper storage or handling or through regrind use, drying may be necessary to prevent splay and odor problems.

Storage

The product can then be stored in standard conditions until processed.

ADDITIONAL INFORMATION

Natural

Natural

Automotive

OEM	STANDARD
Bosch	N28 BN22-X022
Ford	WSB-M4D883-A1
General Motors	GMW17968P-POM-GF20
Renault	No spec listed

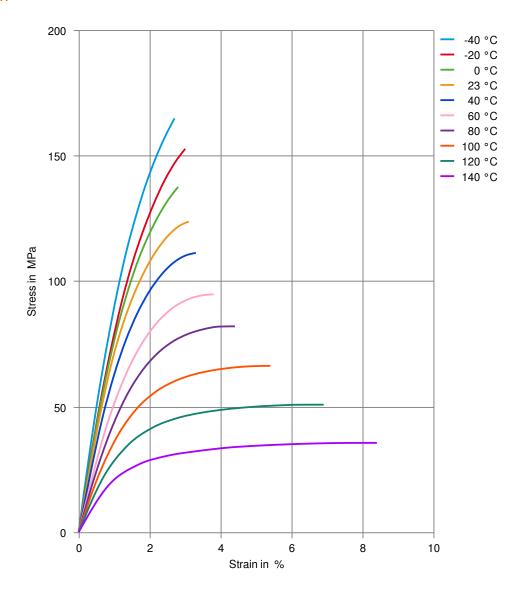
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Stress-strain

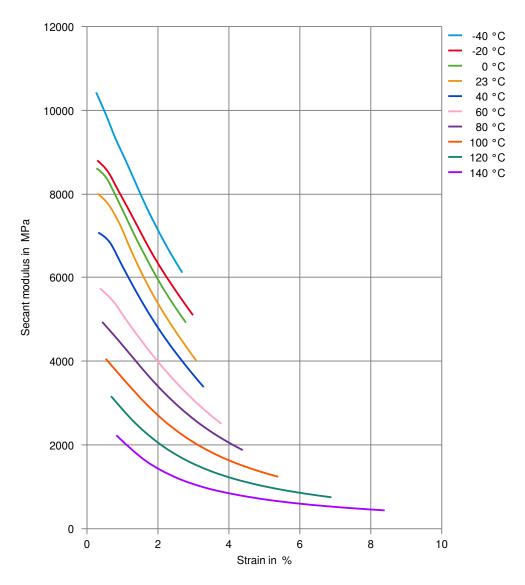






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Secant modulus-strain



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